

HOSTAFORM® C 9021 XAP®

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POM copolymer injection molding grade with medium flow and reduced emissions especially for automotive interior application. Good properties as high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm. VDA 275 Emissions < 10 ppm Ranges of applications: automotive engineering, FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	8 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	2.0 ^[1] %	ISO 294-4, 2577
Moulding shrinkage, normal	1.9 ^[1] %	ISO 294-4, 2577

[1]: @ 195°C

Typical mechanical properties

Tensile modulus	2850 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9 %	ISO 527-1/-2
Nominal strain at break	30 %	ISO 527-1/-2
Flexural modulus	2700 MPa	ISO 178
Flexural strength	89 MPa	ISO 178
Tensile creep modulus, 1h	2500 MPa	ISO 899-1
Tensile creep modulus, 1000h	1300 MPa	ISO 899-1
Charpy impact strength, 23°C	220 ^[P] kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	220 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5 kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C	6 kJ/m ²	ISO 179/1eA
Ball indentation hardness, H 358/30	144 MPa	ISO 2039-1
Poisson's ratio	0.37 ^[C]	

[P]: Partial Break

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	104 °C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110 E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110 E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155 W/(m K)	ISO 22007-2
Effective thermal diffusivity, flow	4.85E-8 m ² /s	ISO 22007-4
Specific heat capacity of melt	2210 J/(kg K)	ISO 22007-4

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Electrical properties

Relative permittivity, 100Hz	4	IEC 62631-2-1
Relative permittivity, 1MHz	4	IEC 62631-2-1
Dissipation factor, 100Hz	20 E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50 E-4	IEC 62631-2-1
Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	35 kV/mm	IEC 60243-1
Comparative tracking index	600	IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m ³	ISO 1183

Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa
Ejection temperature	140 °C

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

Additional information

Injection molding

Preprocessing

To achieve low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

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Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

The product can then be stored in standard conditions until processed.

Automotive

OEM
General Motors
General Motors

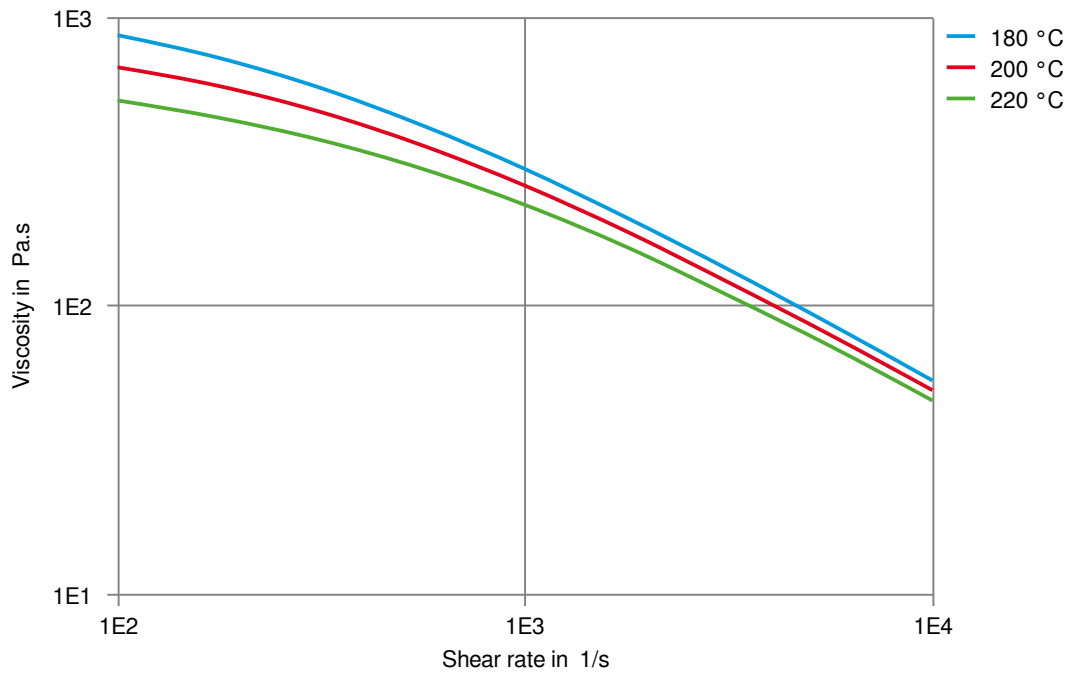
STANDARD
GMW22P-POM-C2
GMW22P-POM-C2

ADDITIONAL INFORMATION
Black
Natural

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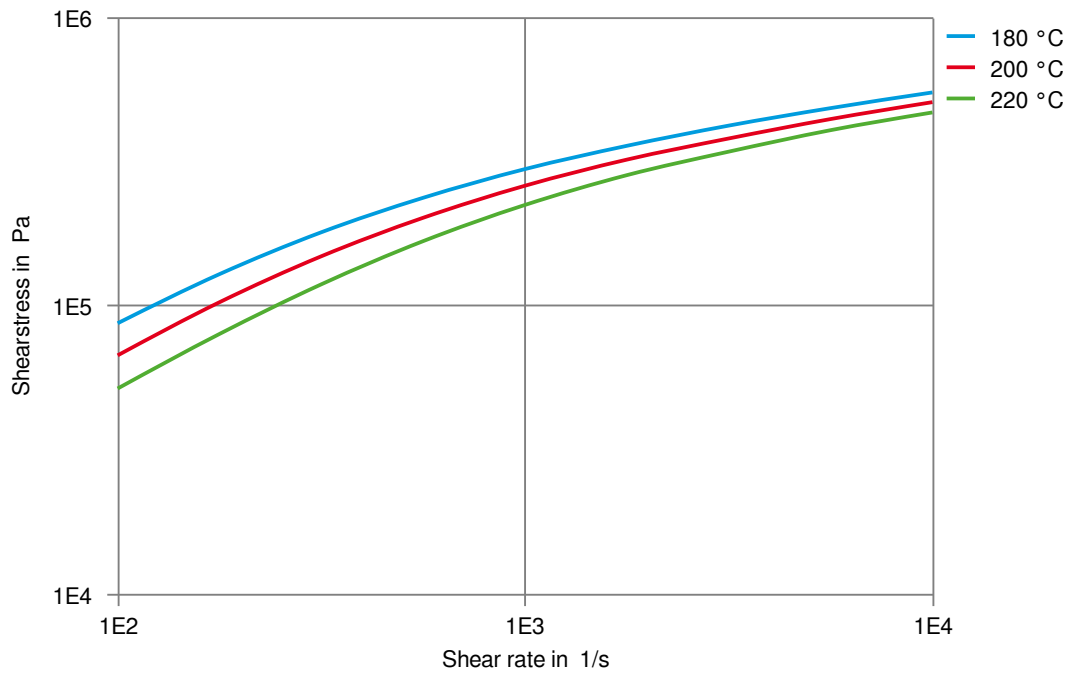
Viscosity-shear rate



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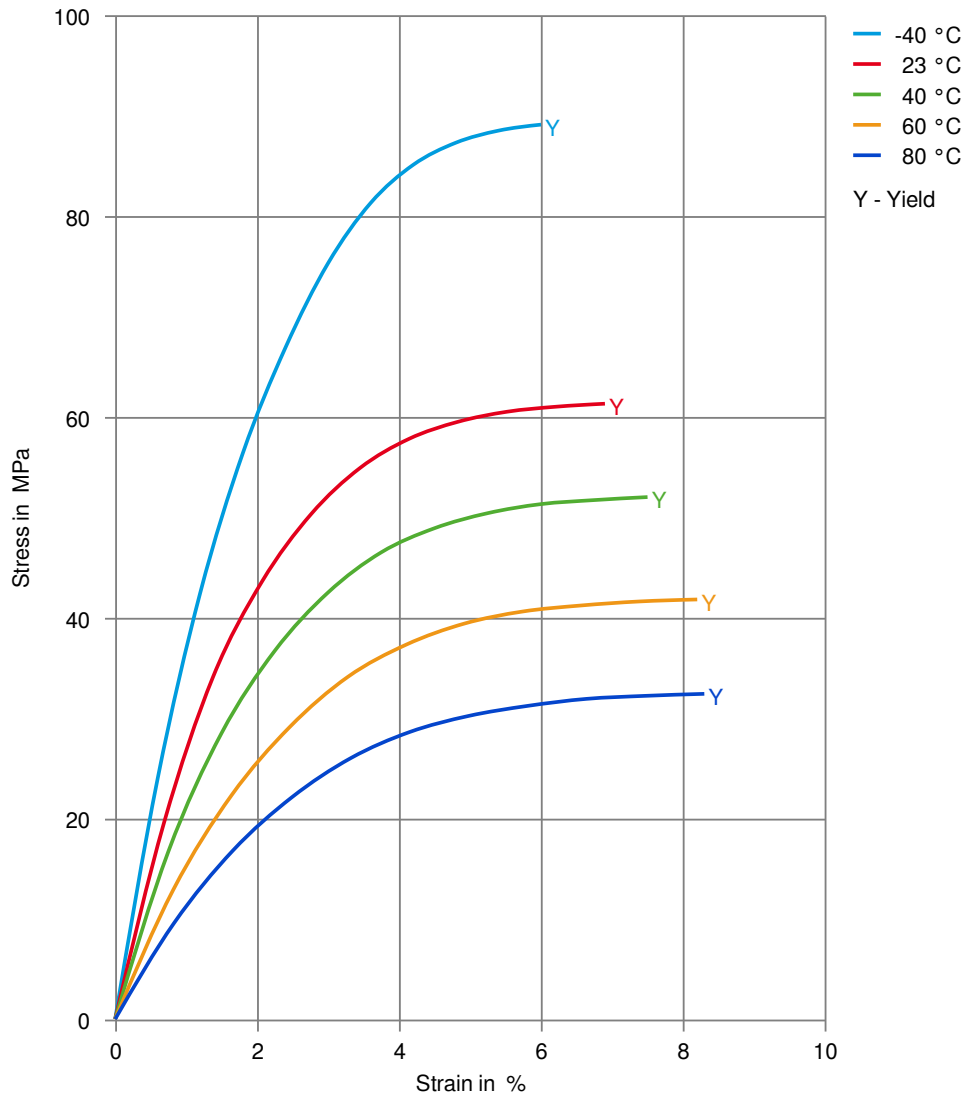
Shearstress-shear rate



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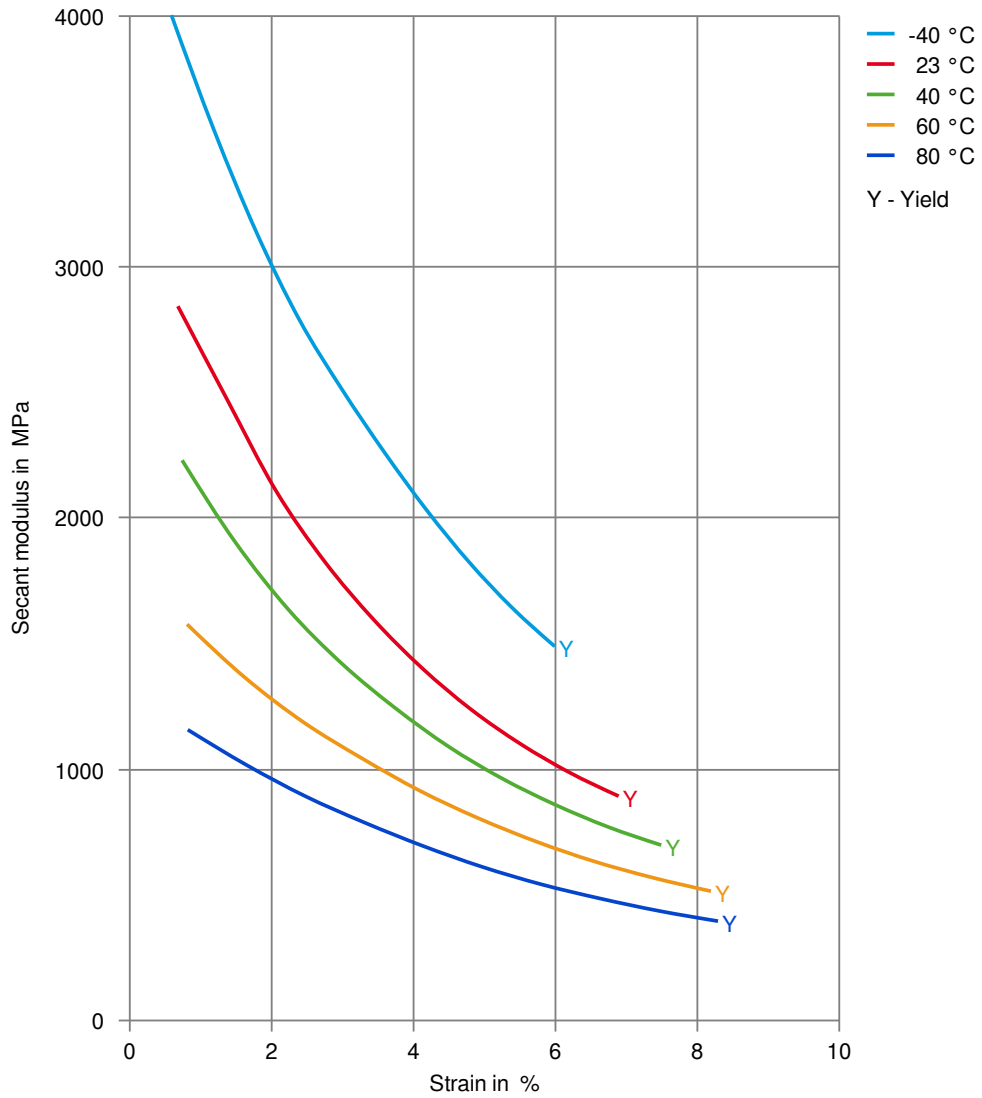
Stress-strain



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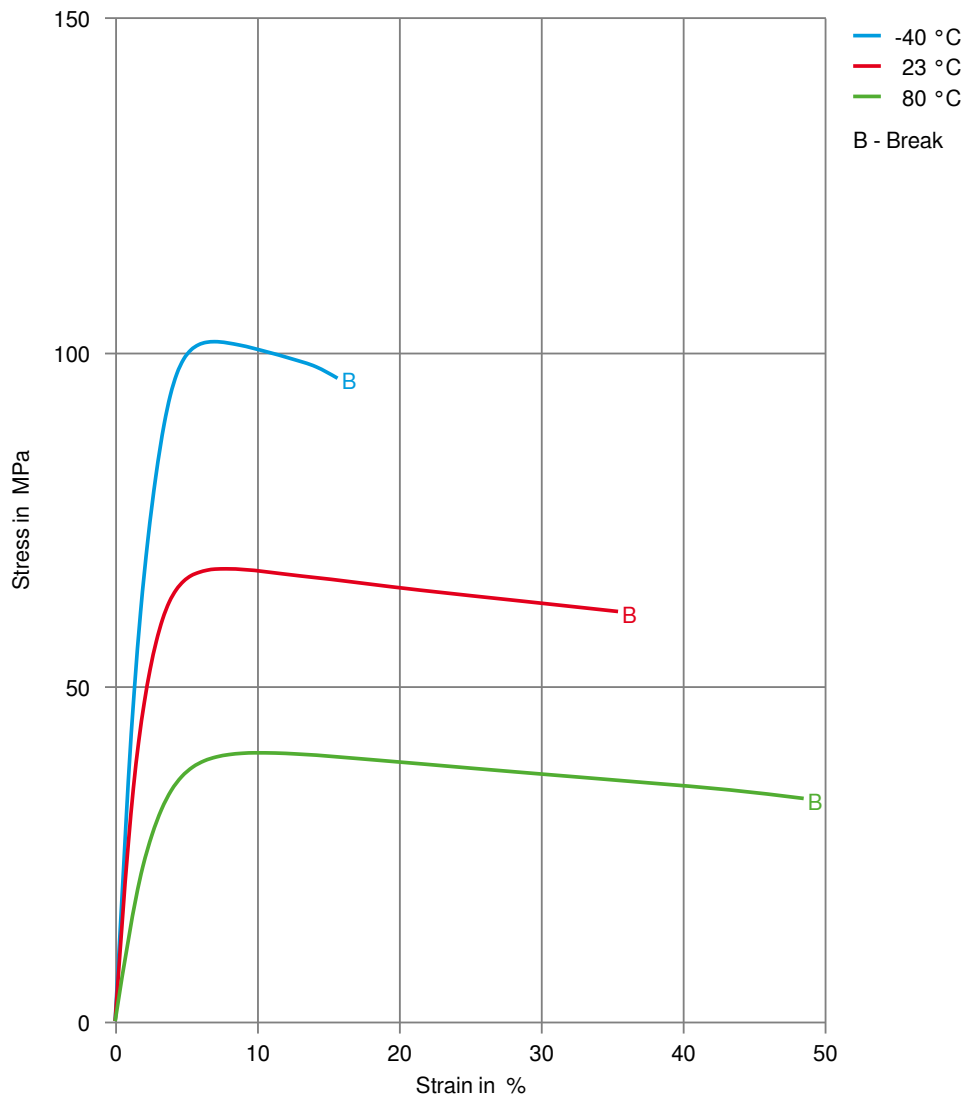
Secant modulus-strain



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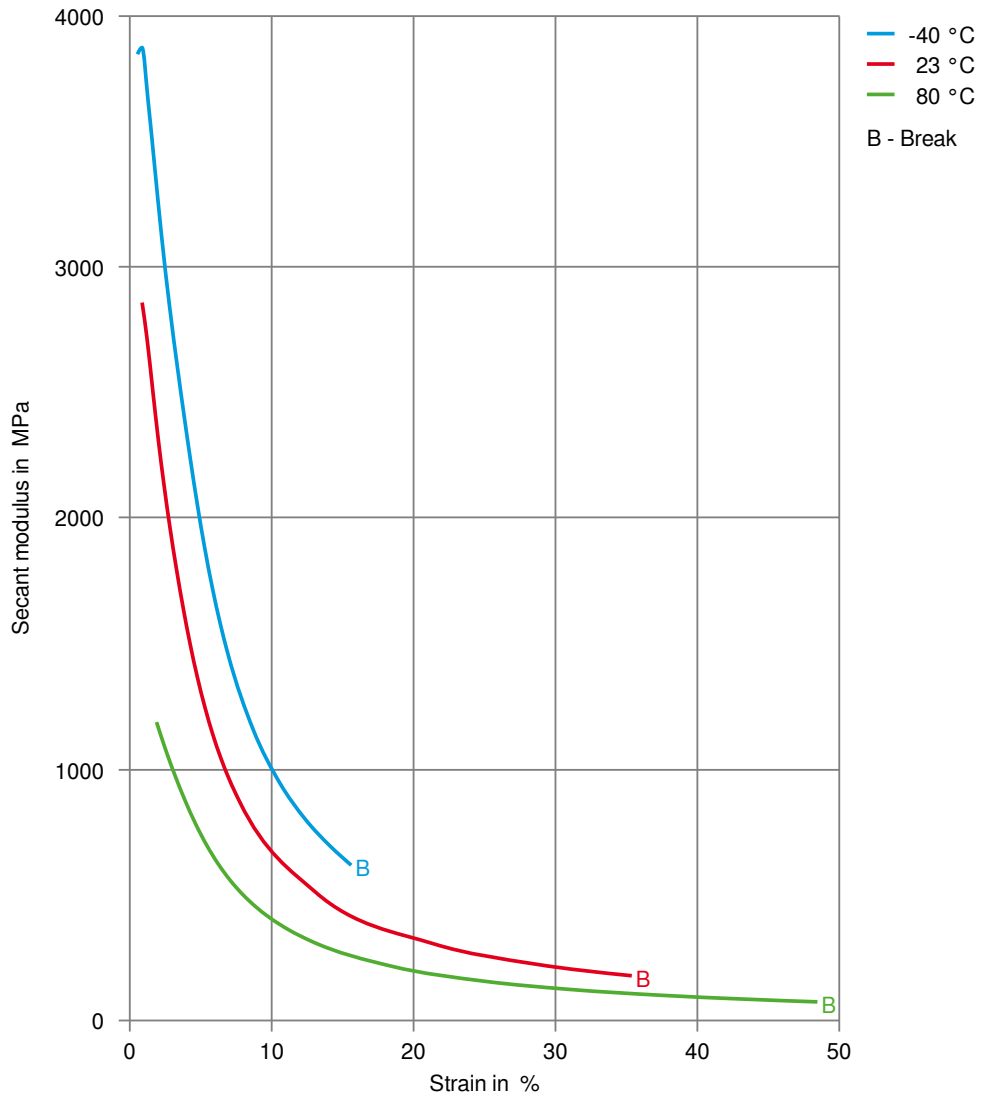
Stress-strain, 50mm/min



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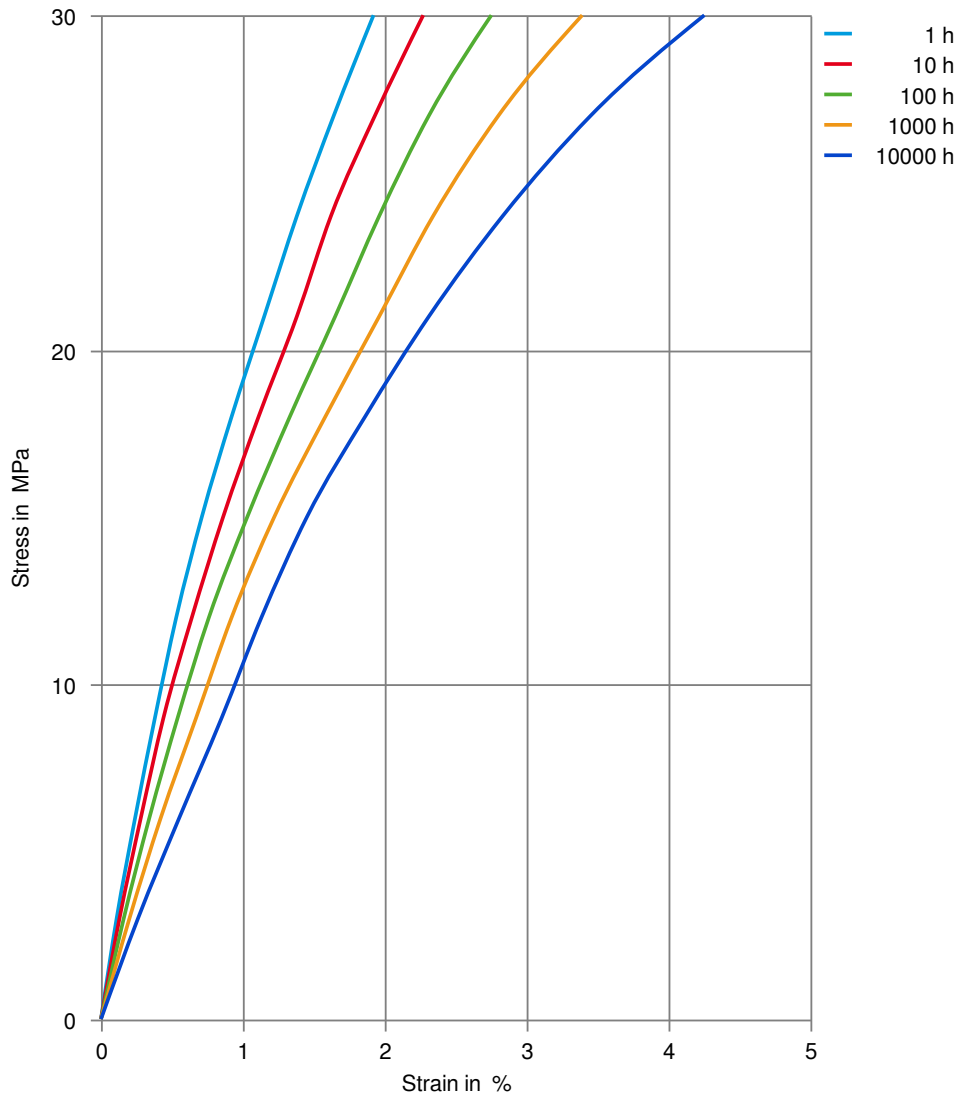
Secant modulus-strain, 50mm/min



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Stress-strain (isochronous) 23°C



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Creep modulus-time 23°C

